

Docket No.: 3749-0106PUS1  
(PATENT)

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

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In re Patent Application of:  
Hiroyuki OSADA et al.

Application No.: 10/551,809

Confirmation No.: 6770

Filed: September 30, 2005

Art Unit: 1641

For: METHOD OF FIXING LOW-MOLECULAR  
COMPOUND TO SOLID-PHASE SUPPORT

Examiner: L. V. Cook

**AMENDMENT IN RESPONSE TO NON-FINAL OFFICE ACTION**

MS Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

SEP 2 2008

Sir:

**INTRODUCTORY COMMENTS**

In response to the Office Action dated May 5, 2008, please amend the above-identified U.S. patent application as follows:

**Amendments to the Specification** begin on page 2 of this paper.

**Amendments to the Abstract** begin on page 5 of this paper.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 6 of this paper.

**Remarks/Arguments** begin on page 10 of this paper.